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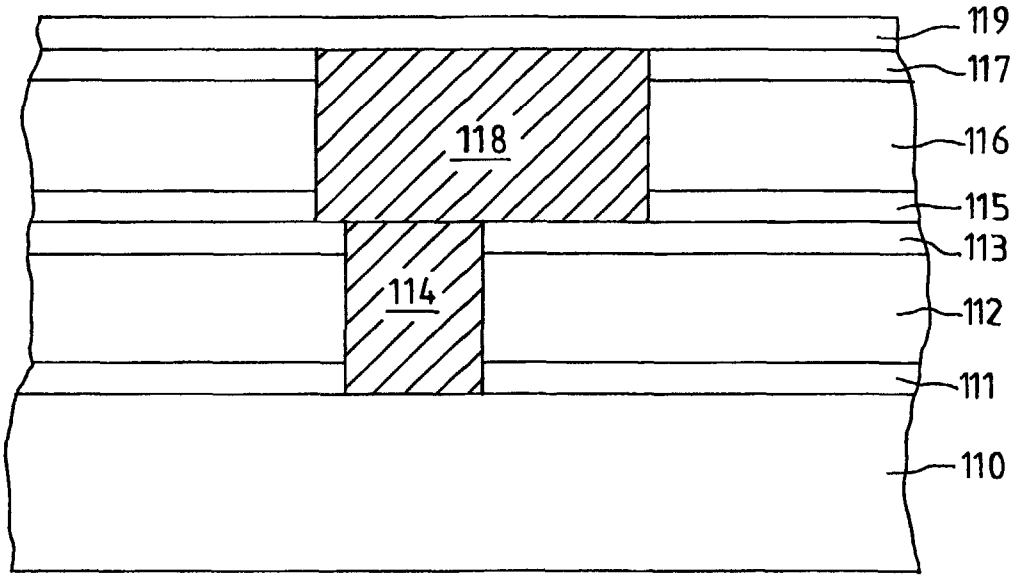
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[Continued on next page]

(54) Title: RELIABLE LOW-K INTERCONNECT STRUCTURE WITH HYBRID DIELECTRIC



(57) Abstract: An advanced back-end-of-line (BEOL) interconnect structure having a hybrid dielectric is disclosed. The inter-layer dielectric (ILD) for the via level is preferably different from the ILD for the line level. In a preferred embodiment, the via-level ILD (112) is formed of a low-k SiCOH material, and the line-level ILD (116) is formed of a low-k polymeric thermoset material.

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